

Data sheet

E-Duplexer Small cell LTE band 13

Series/type: D7901

Ordering code: B30312D7901X942

Date: February 18, 2020

Version: 2.2

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the "RF360 Subsidiaries").



These materials, including the information contained herein, may be used only for informational purposes by the customer. The RF360 Subsidiaries assume no responsibility for errors or omissions in these materials or the information contained herein. The RF360 Subsidiaries reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and the RF360 Subsidiaries assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by QUALCOMM Incorporated or any of its subsidiaries.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of RF360 Europe GmbH.

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.



Table of contents

1 Application	
2 Features	
3 Package	
4 Pin configuration	
5 Matching circuit	
6 Characteristics	
7 Maximum ratings	14
8 Transmission coefficients	
9 Reflection coefficients	18
10 <u>EVMs</u>	19
11 Packing material	
12 Marking	
13 Soldering profile	25
14 Annotations.	
15 Cautions and warnings	27
16 Important notes	28



1 Application

- Enhanced Duplexer for LTE small cell system (Band 13)
- High isolation > 60 dB min
- Usable pass band 10 MHz
- Low VSWR
- RX = uplink = 777 787 MHz
- TX = downlink = 746 756 MHz

2 Features

- Package size 8.1±0.1 mm × 8.1±0.1 mm
- Package height 1.1 mm (max.)
- Approximate weight 0.2 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

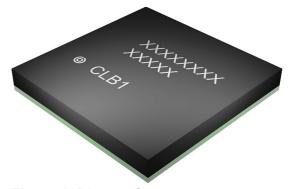
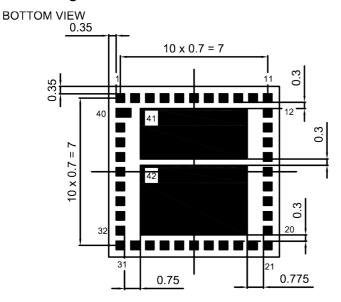


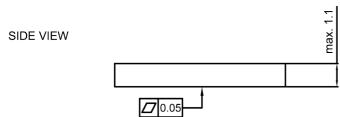
Figure 1: Picture of component with example of product marking.

3 Package

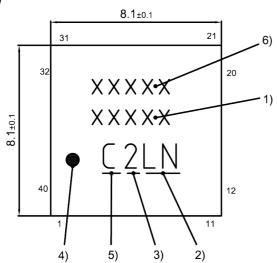


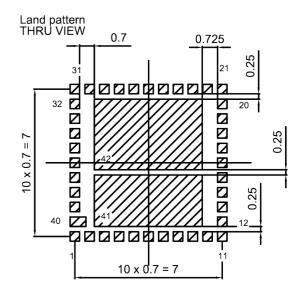
Pad sizes:

Pad 1-39: 0.40 x 0.40 mm² Pad 40: 0.70 x 0.40 mm² Pad 41: 5.075 x 2.395 mm² Pad 42: 5.075 x 3.305 mm² Pad tolerance ±0.05



TOP VIEW





- 6) Tracking ID (5 8 digits)
- 5) Indicating production site C=Wxi)
- 4) Marking for pad number
- 3) Date code acc. EPCOS (day)
- 2) Date code acc. to EN60062 (year, month)
- 1) Position for type designation

Landing pad sizes: Pad 1-39: 0.45 x 0.45 mm² Pad 40: 0.70 x 0.40 mm² Pad 41: 5.125 x 2.445 mm² Pad 42: 5.125 x 3.355 mm²

Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 1.1 mm (max.). See Sec. Package information (p. 27).



Pin configuration

- **3** TX
- RX **1**3
- **2**9 **ANT**
- **1**, 2, 4, 5, Ground
 - 6, 7, 8, 9,
 - 10, 11,
 - 12, 14,
 - 15, 16,
 - 17, 18,
 - 19, 20,
 - 21, 22,
 - 23, 24,
 - 25, 26,
 - 27, 28,
 - 30, 31,

 - 32, 33, 34, 35,

 - 36, 37,
 - 38, 39,
 - 40, 41, 42



5 Matching circuit

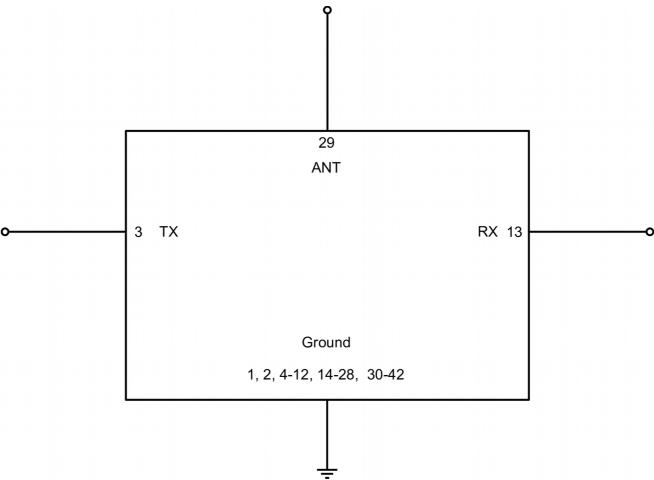


Figure 3: Schematic of matching circuit. No external matching components required.



6 Characteristics

6.1 TX - ANT

Temperature range for specification $T_{\text{SPEC}} = -10 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$

TX terminating impedance $Z_{\rm TX} = 50~\Omega$ ANT terminating impedance $Z_{\rm ANT} = 50~\Omega$ RX terminating impedance $Z_{\rm RX} = 50~\Omega$

Characteristics TX – ANT				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency			f _C	—	751	—	MHz
Insertion attenuation			$\alpha_{\text{INT}}^{-1)}$				
	746 751	MHz	1141	_	2.1	2.7	dB
	751 756	MHz		_	2.1	2.6	dB
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	746 756	MHz	IIIdx	_	2.6	3.5	dB
Amplitude ripple (p-p)			Δα				
	746 756	MHz		_	0.4	1.0	dB
Maximum VSWR			VSWR _{max}				
@ TX port	746 756	MHz	IIIdx	_	1.4	1.8	
@ ANT port	746 756	MHz		_	1.4	1.8	
Maximum error vector magnitude			EVM _{max} ²⁾				
_	748.4 753.6	MHz	IIIdX	_	1.6	3.0	%
Minimum attenuation			$\alpha_{_{min}}$				
	50 150	MHz	min	40	67	_	dB
	150 350	MHz		35	48	_	dB
	350 650	MHz		30	40	_	dB
	698 716	MHz		35	41	_	dB
	716 722	MHz		38	45	_	dB
	777 787	MHz		54	59	_	dB
	788 798	MHz		45	52	_	dB
	798 849	MHz		35	42	_	dB
	1492 1543	MHz		35	38	_	dB
	1554 1574	MHz		35	47	_	dB
	1574 1606	MHz		35	47	_	dB
	1710 1770	MHz		35	47	_	dB
	1850 1915	MHz		35	46	_	dB
	1920 1980	MHz		35	46	_	dB
	2200 2690	MHz		33	41	_	dB
	2690 3800	MHz		25	38	_	dB
	5150 5850	MHz		5	28	_	dB

Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



Temperature range for specification $T_{\text{SPEC}} = -40 \,^{\circ}\text{C} \dots +95 \,^{\circ}\text{C}$

TX terminating impedance $Z_{\text{TX}} = 50 \ \Omega$ ANT terminating impedance $Z_{\text{ANT}} = 50 \ \Omega$ RX terminating impedance $Z_{\text{RX}} = 50 \ \Omega$

Characteristics TX – ANT				$\begin{array}{c} \textbf{min.} \\ \textbf{for } T_{\texttt{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Insertion attenuation			$\alpha_{\text{INT}}^{-1)}$				
	746 751	MHz		_	2.1	2.7	dB
	751 756	MHz		_	2.2	2.6	dB
Maximum insertion attenuation			α_{max}				
	746 756	MHz		_	2.6	3.5	dB
Amplitude ripple (p-p)			Δα				
	746 756	MHz		_	0.6	1.0	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	746 756	MHz		_	1.4	1.8	
@ ANT port	746 756	MHz		_	1.4	1.8	
Maximum error vector magnitude			EVM _{max} ²⁾				
	748.4 753.6	MHz		_	2.3	3.2	%
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	50 150	MHz		40	67	_	dB
	150 350	MHz		35	48	_	dB
	350 650	MHz		30	40	_	dB
	698 716	MHz		35	41	_	dB
	716 722	MHz		38	45	_	dB
	777 787	MHz		54	59	_	dB
	788 798	MHz		45	52	_	dB
	798 849	MHz		35	42	_	dB
	1492 1543	MHz		35	38	_	dB
	1554 1574	MHz		35	47	_	dB
	1574 1606	MHz		35	47	_	dB
	1710 1770	MHz		35	47	_	dB
	1850 1915	MHz		35	46	_	dB
	1920 1980	MHz		35	46	_	dB
	2200 2690	MHz		33	41	_	dB
	2690 3800	MHz		25	38	_	dB
	5150 5850	MHz		5	28	_	dB

Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



6.2 ANT - RX

Europe GmbH

Temperature range for specification $T_{\text{SPEC}} = -10 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$

TX terminating impedance $Z_{\rm TX} = 50~\Omega$ ANT terminating impedance $Z_{\rm ANT} = 50~\Omega$ RX terminating impedance $Z_{\rm RX} = 50~\Omega$

Characteristics ANT – RX				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency			f _C	_	782	_	MHz
Insertion attenuation			$\alpha_{_{INT}}^{1)}$				
	777 782	MHz		_	2.2	2.7	dB
	782 787	MHz		_	2.2	2.7	dB
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	777 787	MHz		_	2.9	3.8	dB
Amplitude ripple (p-p)			Δα				
	777 787	MHz		_	0.6	1.5	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	777 787	MHz		_	1.4	1.8	
@ RX port	777 787	MHz		_	1.3	1.8	
Maximum error vector magnitude			EVM _{max} ²⁾				
	779.4 784.6	MHz		_	2.2	3.0	%
Minimum attenuation			α_{min}				
	50 150	MHz		40	68	_	dB
	150 350	MHz		35	50	_	dB
	350 650	MHz		30	45	_	dB
	728 746	MHz		35	50	_	dB
	746 756	MHz		50	58	_	dB
	758 768	MHz		28	32	_	dB
	808 818	MHz		35	51	_	dB
	859 894	MHz		35	46	_	dB
	1452 1492	MHz		40	56	_	dB
	1554 1574	MHz		40	58	_	dB
	1574 1606	MHz		45	58	_	dB
	1670 1675	MHz		40	58	_	dB
	1930 1995	MHz		40	57	_	dB
	2110 2170	MHz		40	58	_	dB
	2300 2361	MHz		28	37	_	dB
	2361 2690	MHz		30	52	_	dB
	3300 3800	MHz		15	28	_	dB
	5150 5850	MHz		5	20	_	dB

Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



Temperature range for specification $T_{\text{SPEC}} = -40 \,^{\circ}\text{C} \dots +95 \,^{\circ}\text{C}$

TX terminating impedance $Z_{\rm TX} = 50~\Omega$ ANT terminating impedance $Z_{\rm ANT} = 50~\Omega$ RX terminating impedance $Z_{\rm RX} = 50~\Omega$

Characteristics ANT – RX				$\begin{array}{c} \textbf{min.} \\ \textbf{for } T_{\texttt{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Insertion attenuation			$\alpha_{\text{INT}}^{-1)}$				
	777 782	MHz		_	2.2	2.7	dB
	782 787	MHz		_	2.2	2.7	dB
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	777 787	MHz		_	2.9	3.8	dB
Amplitude ripple (p-p)			Δα				
	777 787	MHz		_	0.9	1.5	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	777 787	MHz		_	1.4	1.8	
@ RX port	777 787	MHz		_	1.3	1.8	
Maximum error vector magnitude			EVM _{max} ²⁾				
	779.4 784.6	MHz		_	2.3	3.7	%
Minimum attenuation			$\alpha_{_{min}}$				
	50 150	MHz		40	68	_	dB
	150 350	MHz		35	50	_	dB
	350 650	MHz		30	45	_	dB
	728 746	MHz		35	50	_	dB
	746 756	MHz		50	58	_	dB
	758 768	MHz		28	32	_	dB
	808 818	MHz		35	51	_	dB
	859 894	MHz		35	46	_	dB
	1452 1492	MHz		40	56	_	dB
	1554 1574	MHz		40	58	_	dB
	1574 1606	MHz		45	58	_	dB
	1670 1675	MHz		40	58	_	dB
	1930 1995	MHz		40	57	_	dB
	2110 2170	MHz		40	58	_	dB
	2300 2361	MHz		28	37	_	dB
	2361 2690	MHz		30	52	_	dB
	3300 3800	MHz		15	28	_	dB
	5150 5850	MHz		5	20		dB

Integrated attenuation $\alpha_{_{INT}}$: Averaged power $|S_{_{ii}}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



6.3 TX - RX

Europe GmbH

Temperature range for specification $T_{\text{SPEC}} = -10 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$

TX terminating impedance $Z_{\rm TX} = 50~\Omega$ ANT terminating impedance $Z_{\rm ANT} = 50~\Omega$ RX terminating impedance $Z_{\rm RX} = 50~\Omega$

Characteristics TX – RX				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Isolation			α _{INT} 1)				
	746 756	MHz		65	78	_	dB
	777 787	MHz		65	77	_	dB
Minimum isolation			$\boldsymbol{\alpha}_{min}$				
	746 756	MHz		60	69	_	dB
	777 787	MHz		60	72	_	dB

Integrated attenuation $\alpha_{_{\rm INT}}$: Averaged power $|S_{_{ii}}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.



Temperature range for specification $T_{\text{SPEC}} = -40 \,^{\circ}\text{C} \dots +95 \,^{\circ}\text{C}$

TX terminating impedance $Z_{\text{TX}} = 50 \ \Omega$ ANT terminating impedance $Z_{\text{ANT}} = 50 \ \Omega$ RX terminating impedance $Z_{\text{RX}} = 50 \ \Omega$

Characteristics TX – RX				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Isolation			$\alpha_{\text{INT}}^{-1)}$				
	746 756	MHz		65	78	_	dB
	777 787	MHz		65	77	_	dB
Minimum isolation			$\boldsymbol{\alpha}_{\text{min}}$				
	746 756	MHz		60	69	_	dB
	777 787	MHz		60	72	_	dB

Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.



7 **Maximum ratings**

Operable temperature	T _{OP} = -40 °C +95 °C	
Storage temperature	T _{STG} ¹⁾ = -40 °C +95 °C	
DC voltage	$ V_{DC} ^{2} = 0 \text{ V (max.)}$	
ESD voltage	$V_{\rm ESD}^{3)} = 50 \text{ V (max.)}$	Machine model.
Input power	P _{IN}	
@ TX port: 746 756 MHz	31 dBm ⁴⁾	5 MHz LTE downlink signal (25 RB) for 100000 h @ 55 °C. P _{IN} average – 42 dBm
		peak. Source and load impedance 50 Ω .
@ TX port: other frequency ranges	10 dBm	Source and load impedance 50 Ω .

Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C. In case of applied DC voltage blocking capacitors are mandatory.

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

Expected lifetime according to accelerated power durability simulations, and wear out models.

²⁾

³⁾



Europe GmbH

8 Transmission coefficients

o manishingsion coefficients

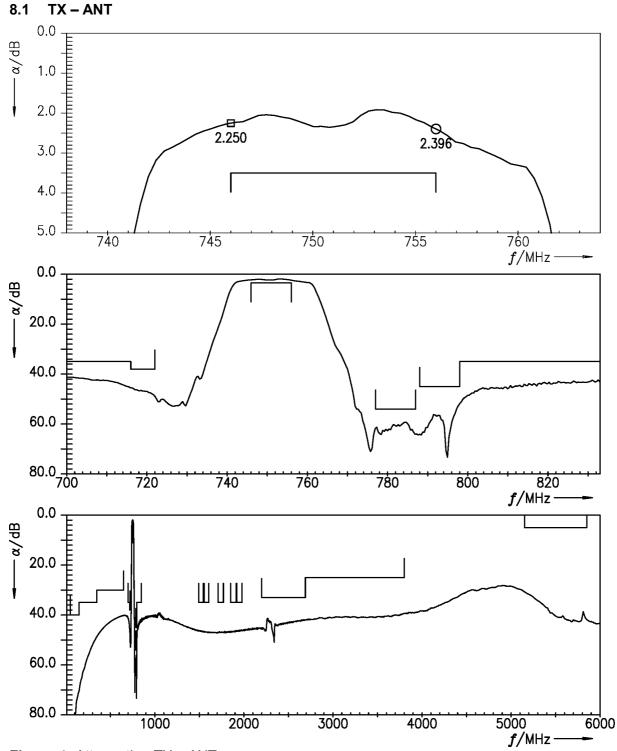


Figure 4: Attenuation TX – ANT.

Europe GmbH

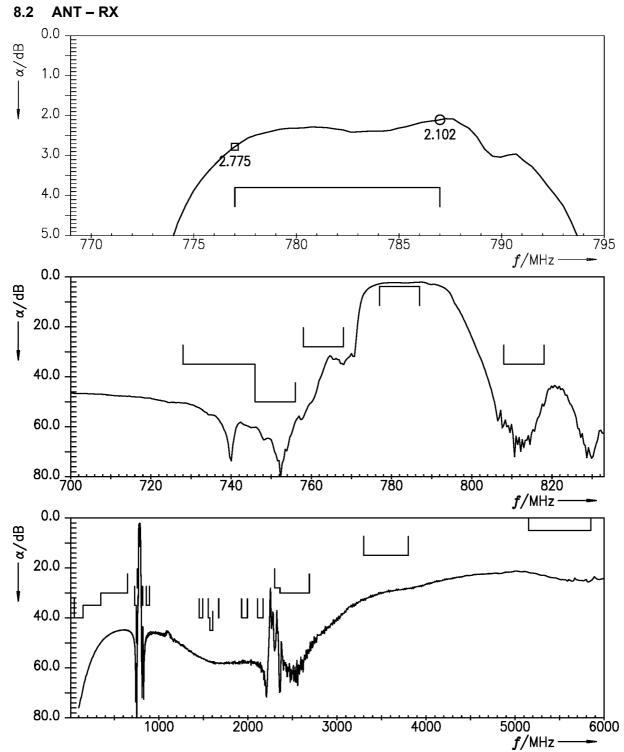


Figure 5: Attenuation ANT – RX.

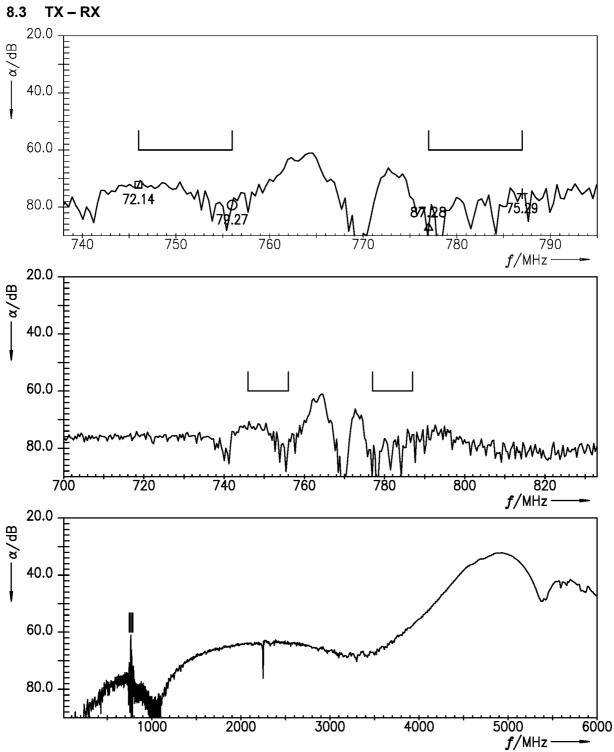
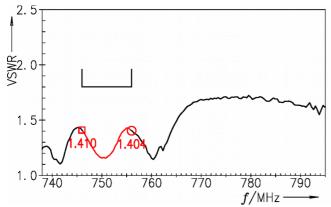


Figure 6: Isolation TX – RX.



9 Reflection coefficients



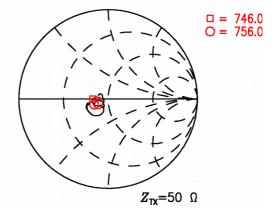
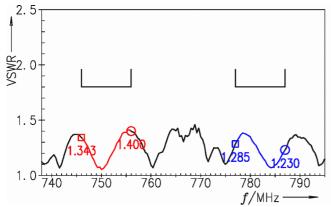


Figure 7: Reflection coefficient at TX port.



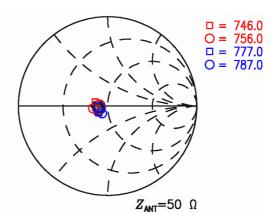
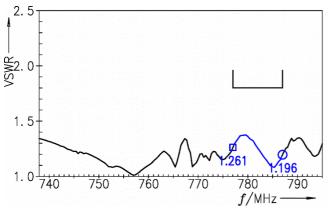


Figure 8: Reflection coefficient at ANT port.



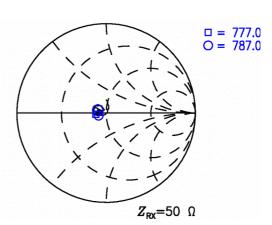


Figure 9: Reflection coefficient at RX port.

10 EVMs

10.1 TX - ANT

Europe GmbH

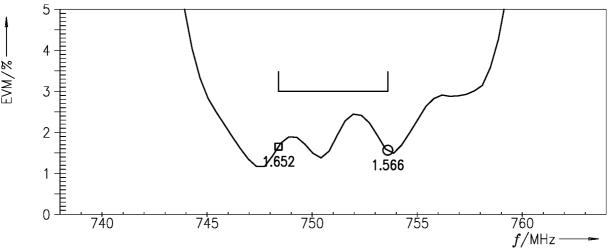


Figure 10: Error vector magnitude TX – ANT.

10.2 ANT - RX

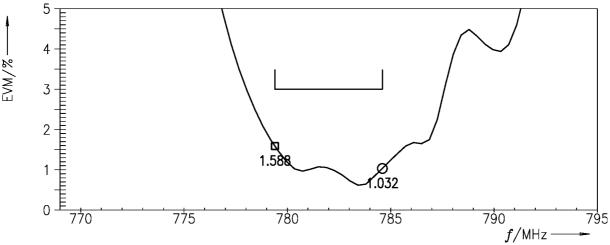


Figure 11: Error vector magnitude ANT – RX.



11 Packing material

11.1 Tape

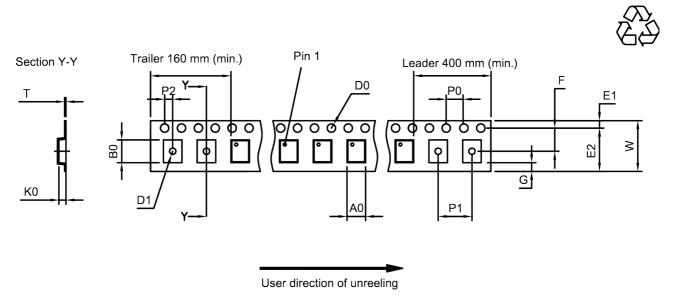


Figure 12: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	8.4±0.05 mm	_	E ₂	14.25 mm (min.)	_	P ₁	12.0±0.1 mm
B ₀	8.4±0.05 mm		F	7.5±0.1 mm		P_2	2.0±0.1 mm
D ₀	1.5+0.1/-0 mm	_	G	0.75 mm (min.)	_	Т	0.3±0.05 mm
D ₁	1.5 mm (min.)		K ₀	1.3±0.1 mm		W	16.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	- –	Po	4.0 _{±0.1} mm	- -		

Table 1: Tape dimensions.



Europe GmbH

11.2 Reel with diameter of 330 mm

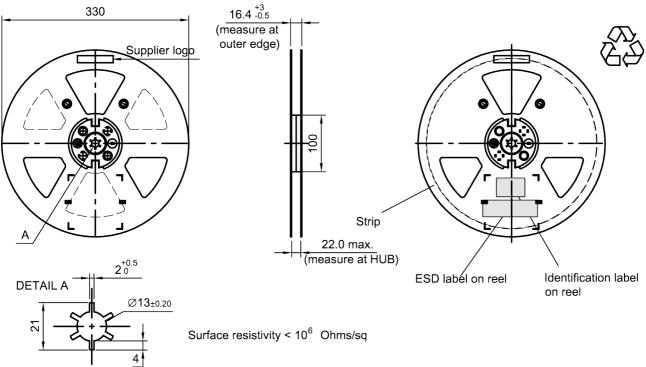


Figure 13: Drawing of reel (first-angle projection) with diameter of 330 mm.

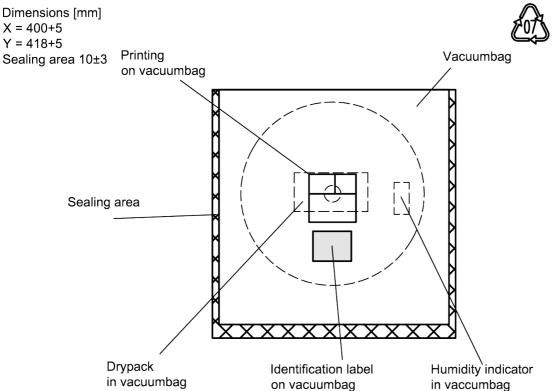


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

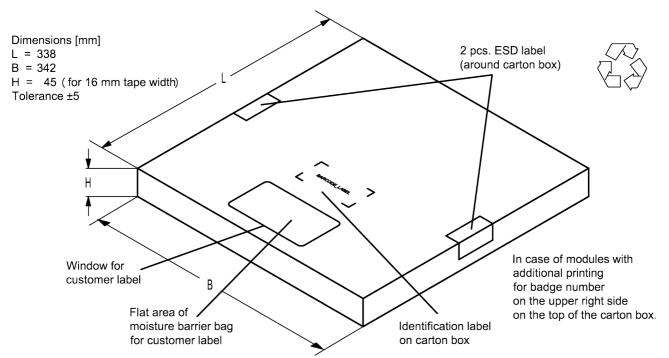


Figure 15: Drawing of folding box for reel with diameter of 330 mm.



12 Marking

Products are marked with tracking number (5 or 8 characters), type designator (5 characters), as well as production location and date code (4 characters). The marking corresponds to one of the following schemes:

XXXXX	5-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 2: Marking for 5-character tracking number (standard).

XXXXXXXX	8-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 3: Marking for 8-character tracking number.

???	
XXXXXXXX	8-character tracking number
XXXXX	5-character type designator
M5C6	1-character location code + 3-character date code (example)

Table 4: Marking for 8-character tracking number with 4 lines.

■ Tracking number: t.b.d.

■ Type designator: The 5-character type designator of the ordering code is used for the marking.

Example: B3xxxx**D1234**xxxx

■ Production-location and date code: The production-location is encoded in the first character according to Table 5. The production date code is encoded in the last three characters according to Table 6.

Code:	M or no letter	J	С	Н	
Location:	Munich	Singapore	Wuxi	SAE, Hong Kong	

Table 5: Production location code.



1 st digit (day)				2 nd digit (year)			3 rd digit (month)						
Day	Code	Day	Code	Day	Code	Year	Code	Year	Code	Month	Code	Month	Code
1	1	11	Α	21	М	2010	Α	2022	Р	Jan	1	Jul	7
2	2	12	В	22	N	2011	В	2023	R	Feb	2	Aug	8
3	3	13	С	23	Р	2012	С	2024	S	Mar	3	Sep	9
4	4	14	D	24	R	2013	D	2025	Т	Apr	4	Oct	0
5	5	15	Е	25	S	2014	Е	2026	U	May	5	Nov	N
6	6	16	F	26	Т	2015	F	2027	V	Jun	6	Dec	D
7	7	17	Н	27	U	2016	Н	2028	W				
8	8	18	J	28	V	2017	J	2029	Х				
9	9	19	K	29	W	2018	K	2030	Z				
10	0	20	L	30	Х	2019	L	2031	Α				
				31	Z	2020	М	2032	В				
						2021	N	and	so on				

Table 6: Production date code.

Example of how to decode production location and date code:

Code: M5C6



13 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s		
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s		
T > 220 °C	30 s to 70 s		
T > 230 °C	min. 10 s		
T > 245 °C	max. 20 s		
<i>T</i> ≥ 255 °C	-		
peak temperature T_{peak}	250 °C +0/-5 °C		
wetting temperature T_{\min}	230 °C +5/-0 °C for 10 s ± 1 s		
cooling rate	≤ 3 K/s		
soldering temperature T	measured at solder pads		

Table 7: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

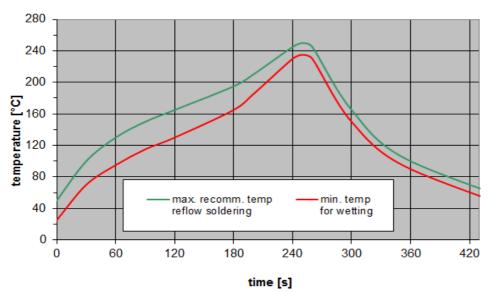


Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.



14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

Ordering code	Packing unit
B30312D7901X942	3000 pcs

Table 8: Ordering codes and packing units.



15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.gualcomm.com/.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



16 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (https://rffe.qualcomm.com). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available.

The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

单击下面可查看定价,库存,交付和生命周期等信息

>>Qualcomm-RF360